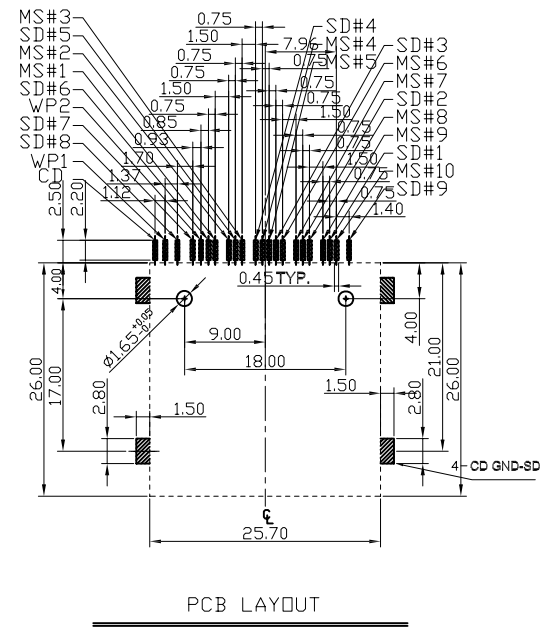


锐泰科
 2008.10.10
 工程部

| MS CARD PIN DESIGN | | SD CARD PIN DESIGN | |
|--------------------|---------|--------------------|------------------------------|
| Pin# | Name | Pin# | Name |
| 1# | VSS | 1# | CD/DAT3 Card Detect/DATA 1/0 |
| 2# | BS | 2# | CMD COMMAND |
| 3# | VCC | 3# | Vss1 GROUND |
| 4# | DIO | 4# | V _{DD} POWER |
| 5# | RESERVE | 5# | CLK Clock |
| 6# | INS | 6# | Vss2 GROUND |
| 7# | RESERVE | 7# | DAT0 Data 1/0 |
| 8# | SCLK | 8# | DAT1 Data 1/0 |
| 9# | VCC | 9# | DAT2 Data 1/0 |
| 10# | VSS | | |

NOTES:
MATERIALS:
 HOUSING : ENGINEERING THERMOPLASTIC
 UL 94V-0. BLACK IN COLOUR
 CONTACT : COPPER ALLOY
 COVER : COPPER ALLOY
FINISH:
 CONTACT AREA: GOLD OVER NICKEL.
 SOLDER AREA : TIN OVER NICKEL.
PERFORMANCE CHARACTERISTICS:
 CURRENT RATING : 0.5 A AC DC
 VOLTAGE RATING : 500VAC MIN.
 CONTACT RESISTANCE : 100mΩ MAX.
 INSULATION RESISTANCE : 1000MΩ MIN . AT 500VDC.
 OPERATING TEMPERATUER : -25°C TO 85°C.



| | | | | | | | | |
|--|---|---|--|------------------|------------------|----------------|----|------|
| UNLESS OTHERWISE SPECIFIED TOLERANCE TO BE | DRN: NEIL | DATE: 2008.10.10 | A | 新发行 | NEIL | 2008.10.10 | | |
| | LINEAR X ± 0.38 XX ± 0.25 XXX ± 0.10 | ANGULAR X. ± 2° .X ± 1° .XX ± 0.5° | CKD: DAVID | DATE: 2008.10.10 | REV. | CHANGE DETAILS | BY | DATE |
| BREAK ALL SHARP EDGES AND REMOVE ALL BURRS | APP'D: KING | DATE: 2008.10.10 | TITLE: SD+MMC+MS 3IN1CARD A Type | | RETC深圳市锐泰科电子有限公司 | | | |
| DO NOT SCALE | SCALE: 1:1 | THIRD ANGLE PROJECTION | DRAWING NO. | | SHEET 1/1 | | | |
| DIMENSIONS IN MILLIMETRES | | PART NO.: | | SIZE: A4 | | | | |